



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4473G V55-2		<b>Issued</b>		28. August 2013		
<b>MA#</b>		MA000668590						
<b>Package</b>		PG-DSO-12-11		<b>Weight*</b>		403.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.438	1.84	1.84	18417	18417
leadframe	non noble metal	iron	7439-89-6	0.230	0.06		571	
	inorganic material	phosphorus	7723-14-0	0.069	0.02		171	
	non noble metal	copper	7440-50-8	230.106	56.97	57.05	569766	570508
wire	non noble metal	aluminium	7429-90-5	0.143	0.04	0.04	354	354
encapsulation	organic material	carbon black	1333-86-4	0.309	0.08		765	
	plastics	epoxy resin	-	14.209	3.52		35183	
	inorganic material	silicondioxide	60676-86-0	139.929	34.65	38.25	346477	382425
leadfinish	non noble metal	tin	7440-31-5	4.235	1.05	1.05	10487	10487
plating	non noble metal	nickel	7440-02-0	0.177	0.04		438	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.04	1	439
solder	noble metal	silver	7440-22-4	0.175	0.04		434	
	non noble metal	tin	7440-31-5	0.140	0.03		347	
	non noble metal	lead	7439-92-1	6.700	1.66	1.73	16589	17370
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com